深圳市凯越翔电子有限公司

声表谐振器规格书

产品名称：	声表谐振器
产品型号：	TO-39/R315
产品参数：	±75KHZ
原厂型号：	KTOR3150
凯越翔技术部：	董宗全

客 户 确 认 栏	
认 证 印 章 年 月 日	负 责 人 印 章 年 月 日

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1. SCOPE

This specification shall cover the characteristics of 1-port SAW resonator with used for remote-control security.

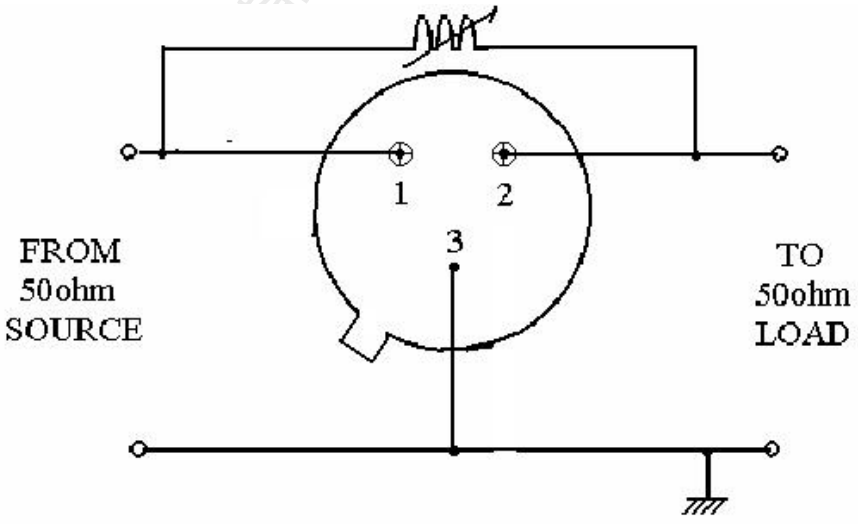
2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-20℃ to +70℃
Storage temperature	-40℃ to +85℃
RF Power Dissipation	0dBm

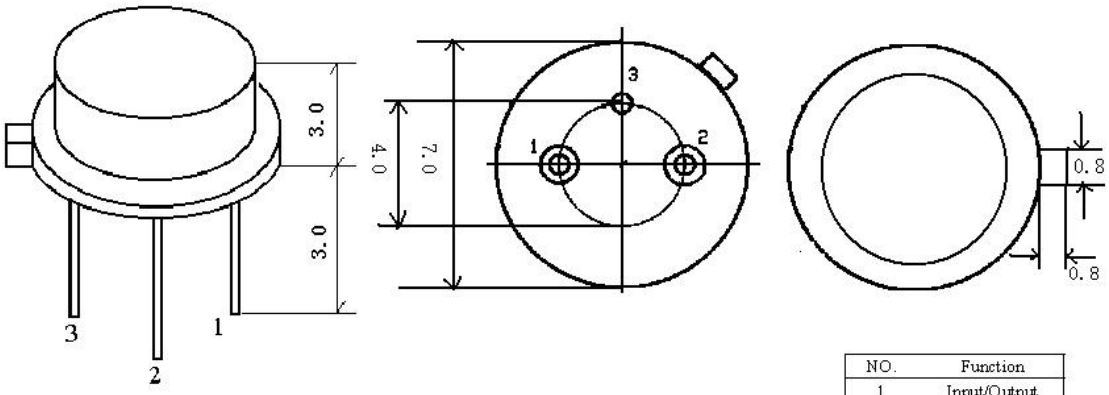
2.2Electronic Characteristics

Item		Unites	Minimum	Typical	Maximum
Center Frequency		MHz	314.925	315	315.075
Insertion Loss		dB		1.5	2.5
Quality Factor Unload Q			5000	12800	
50Ω Loaded Q			1000	2000	
Temperature Stability	Turnover Temperature	℃	10	25	40
	Freq.temp.Coefficient	ppm/℃2		0.032	
Frequency Aging		ppm/yr		<±10	
DC. Insulation Resistance		MΩ	1.0		
RF Equivalent RLC Model	Motional Resistance R1	Ω		19	26
	Motional Inductance L1	μH		92.929	
	Motional Capacitance C1	fF		1.4475	
Transducer Static Capacitance		pF		1.95	

3. TEST CIRCUIT



4. DIMENSION



NO.	Function
1	Input/Output
2	Input/Output
3	GND

5. ENVIRONMENTAL CHARACTERISTICS

5-1 High temperature exposure

Subject the device to +85℃ for 16 hours. Then release the resonator into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

5-2 Low temperature exposure

Subject the device to -40℃ for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

5-3 Temperature cycling

Subject the device to a low temperature of -45℃ for 30 minutes. Following by a high temperature of +85℃ for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2.2.

5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260℃ ±10℃ for 10±1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2.2.

5-5 Solderability

Subject the device terminals into the solder bath at 245℃ ±5℃ for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 2.2.

5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2.2.

5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2.2.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration &destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.

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